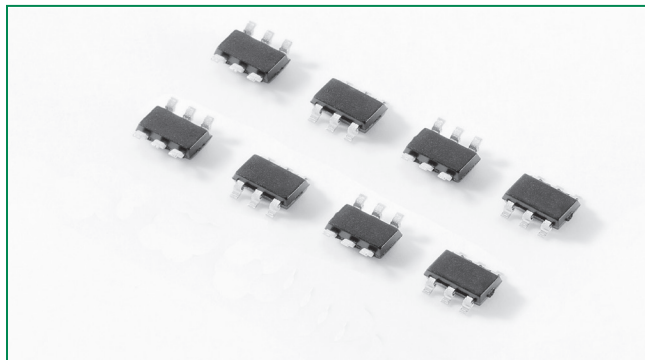


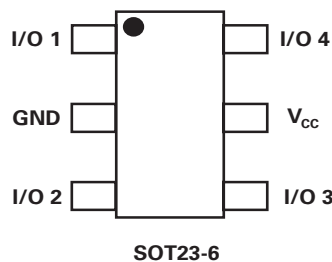
SP0504S Series 0.85pF Diode Array



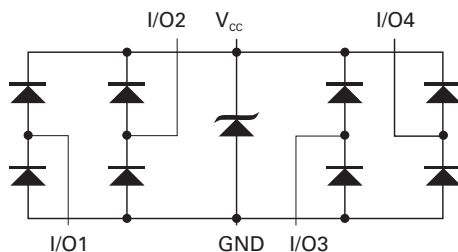
Description

The SP0504S has ultra low capacitance rail-to-rail diodes with an additional zener diode fabricated in a proprietary silicon avalanche technology to protect each I/O pin providing a high level of protection for electronic equipment that may experience destructive electrostatic discharges (ESD). These robust diodes can safely absorb repetitive ESD strikes at the maximum level (Level 4) specified in the IEC 61000-4-2 international standard without performance degradation. Their very low loading capacitance also makes them ideal for protecting high speed signal pins such as HDMI, DVI, USB2.0, and IEEE 1394.

Pinout



Functional Block Diagram



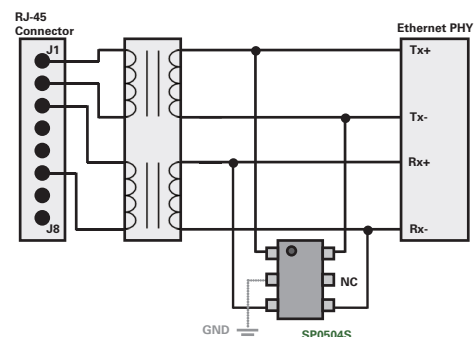
Features

- Low capacitance of 0.85 pF (TYP) per I/O
- ESD protection of $\pm 12\text{kV}$ contact discharge, $\pm 15\text{kV}$ air discharge, (IEC61000-4-2)
- EFT protection, IEC61000-4-4, 40A (5/50ns)
- Low leakage current of 0.5 μA (MAX) at 5V
- Small packaging options saves board space
- Lightning Protection, IEC61000-4-5, 4.5A (8/20 μs)

Applications

- Computer Peripherals
- Mobile Phones
- PDA's
- Digital Cameras
- Network Hardware/Ports
- Test Equipment
- Medical Equipment

Application Example



A single 4 channel SP0504S device can be used to protect four of the data lines in a HDMI/DVI interface. Two (2) SP0504S devices provide protection for the main data lines. Low voltage ASIC HDMI/DVI drivers can also be protected with the SP0504S, the $+V_{CC}$ pins on the SP0504S can be substituted with a suitable bypass capacitor or in some backdrive applications the $+V_{CC}$ of the SP0504S can be floated or NC.

Life Support Note:

Not Intended for Use in Life Support or Life Saving Applications

The products shown herein are not designed for use in life sustaining or life saving applications unless otherwise expressly indicated.

Absolute Maximum Ratings

Symbol	Parameter	Value	Units
I_{PP}	Peak Current ($t_p=8/20\mu s$)	4.5	A
T_{OP}	Operating Temperature	-40 to 85	°C
T_{STOR}	Storage Temperature	-50 to 150	°C

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

Thermal Information

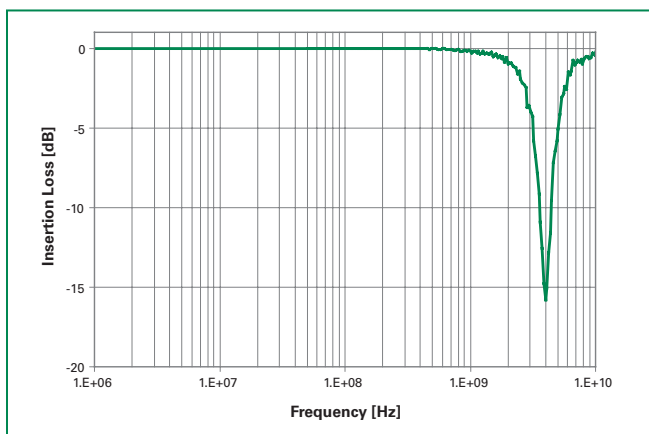
Parameter	Rating	Units
Storage Temperature Range	-65 to 150	°C
Maximum Junction Temperature	150	°C
Maximum Lead Temperature (Soldering 20-40s)	260	°C

Electrical Characteristics ($T_{OP}=25^{\circ}C$)

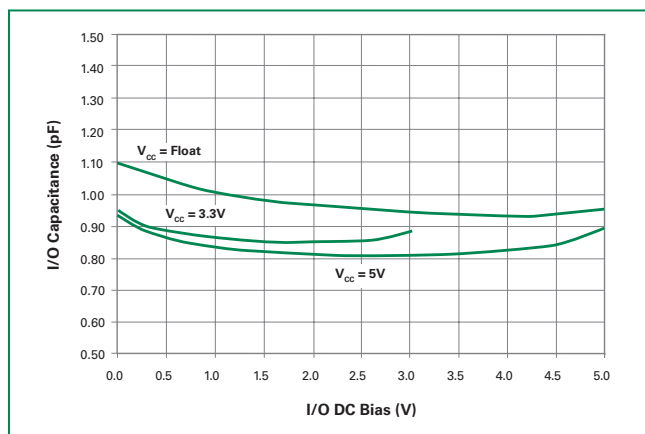
Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
Reverse Standoff Voltage	V_{RWM}	$I_R \leq 1\mu A$			6.0	V
Reverse Leakage Current	I_{LEAK}	$V_R=5V$			0.5	μA
Clamp Voltage ¹	V_C	$I_{PP}=1A, t_p=8/20\mu s, Fwd$		9.5	11.0	V
		$I_{PP}=2A, t_p=8/20\mu s, Fwd$		10.6	13.0	V
ESD Withstand Voltage ¹	V_{ESD}	IEC61000-4-2 (Contact)	± 12			kV
		IEC61000-4-2 (Air)	± 15			kV
Diode Capacitance ¹	$C_{I/O-GND}$	Reverse Bias=0V	0.95	1.1	1.25	pF
		Reverse Bias=1.65V	0.7	0.85	1.0	pF
Diode Capacitance ¹	$C_{I/O-I/O}$	Reverse Bias=0V		0.5		pF

Note: 1. Parameter is guaranteed by design and/or device characterization.

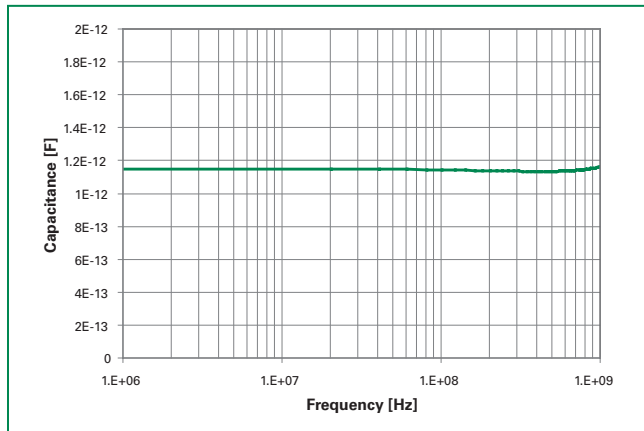
Insertion Loss (S21) I/O to GND



Capacitance vs. Bias Voltage



Capacitance vs. Frequency



Product Characteristics

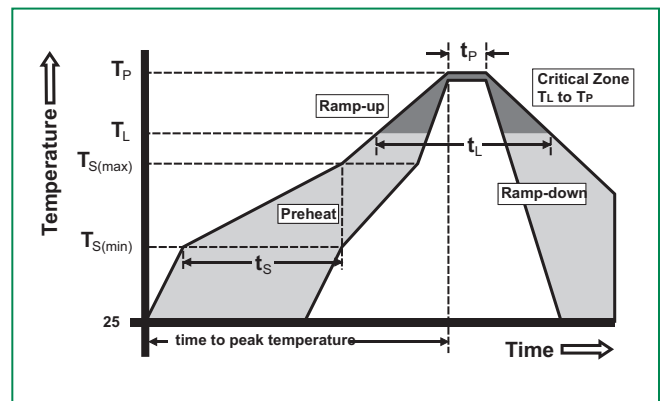
Lead Plating	Matte Tin
Lead Material	Copper Alloy
Lead Coplanarity	0.0004 inches (0.102mm)
Substrate Material	Silicon
Body Material	Molded Epoxy
Flammability	UL 94 V-0

Notes :

1. All dimensions are in millimeters
2. Dimensions include solder plating.
3. Dimensions are exclusive of mold flash & metal burr.
4. Blo is facing up for mold and facing down for trim/form, i.e. reverse trim/form.
5. Package surface matte finish VDI 11-13.

Soldering Parameters

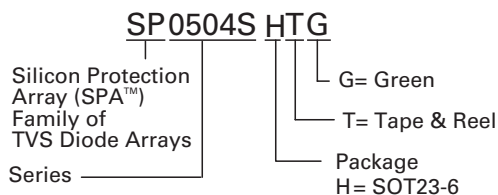
Reflow Condition		Pb – Free assembly
Pre Heat	- Temperature Min ($T_{s(min)}$)	150°C
	- Temperature Max ($T_{s(max)}$)	200°C
	- Time (min to max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus) Temp (T_L) to peak		3°C/second max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/second max
Reflow	- Temperature (T_L) (Liquidus)	217°C
	- Temperature (t_L)	60 – 150 seconds
Peak Temperature (T_p)		260 ^{+0/-5} °C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_p)		8 minutes Max.
Do not exceed		260°C



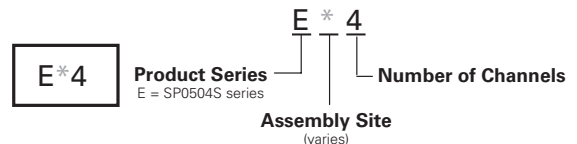
Ordering Information

Part Number	Package	Marking	Min. Order Qty.
SP0504SHTG	SOT23-6	E * 4	3000

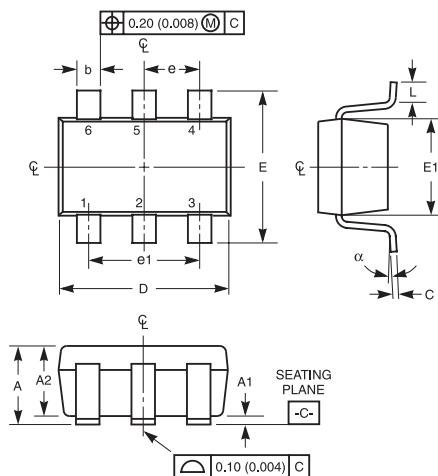
Part Numbering System



Part Marking System

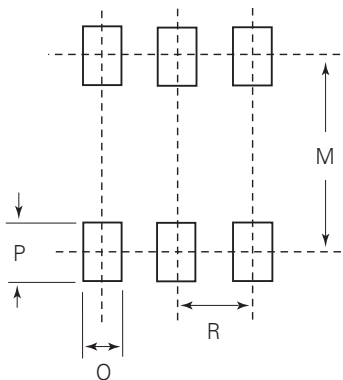


Package Dimensions — SOT23-6



Package	SOT23				
Pins	6				
JEDEC	MO-178AB				
	Millimeters		Inches		Notes
	Min	Max	Min	Max	
A	0.900	1.450	0.035	0.057	-
A1	0.000	0.150	0.000	0.006	-
A2	0.900	1.300	0.035	0.051	-
b	0.350	0.500	0.0138	0.0196	-
C	0.080	0.220	0.0031	0.009	-
D	2.800	3.000	0.11	0.118	3
E	2.600	3.000	0.102	0.118	-
E1	1.500	1.750	0.06	0.069	3
e	0.95 Ref		0.0374 ref		-
e1	1.9 Ref		0.0748 Ref		-
L	0.30	0.600	0.012	0.023	4,5
N	6		6		6
α	0°	8°	0°	8°	-
M		2.590		0.102	-
O		0.690		.027 TYP	-
P		0.990		.039 TYP	-

Recommended Solder Pad Layout

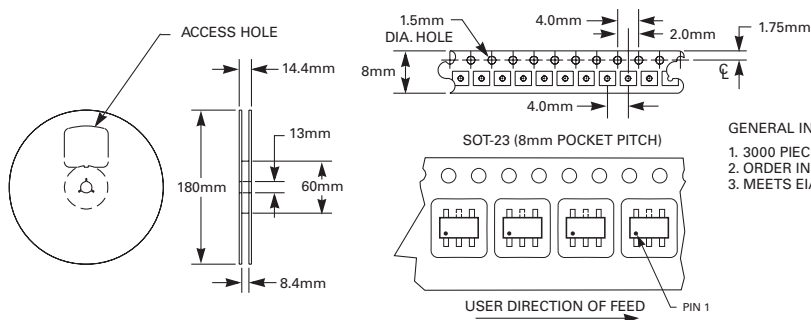


Notes:

1. Dimensioning and tolerancing Per ASME Y14.5M-1994.
2. Package conforms to EIAJ SC-74 (1992).
3. Dimensions D and E1 are exclusive of mold flash, protrusions, or gate burrs.
4. Foot length L measured at reference to seating plane.
5. "L" is the length of flat foot surface for soldering to substrate.
6. "N" is the number of terminal positions.
7. Controlling dimension: MILLIMETER. Converted inch dimensions are not necessarily exact.

Embossed Carrier Tape & Reel Specification — SOT23-6

8mm TAPE AND REEL



GENERAL INFORMATION

1. 3000 PIECES PER REEL.
2. ORDER IN MULTIPLES OF FULL REELS ONLY.
3. MEETS EIA-481 REVISION "A" SPECIFICATIONS.